

ABSTRACT

UNDERFILL APPLICATIONS USING FILM TECHNOLOGY

A method and apparatus are provided for assembling a semiconductor package. The invention uses a thin release film placed over package components in a mold cavity. The release film is drawn down over the assembled components and envelops the
5 assembled components with an airtight seal around at least three sides for assisting and defining the flow of encapsulant into empty space between components. A mold compound is flowed into the empty space, assisted by vacuum or air pressure at the airtight seal. The release film is pulled up and away from the assembled components, permitting encapsulant to flow into the remainder of the mold cavity.

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